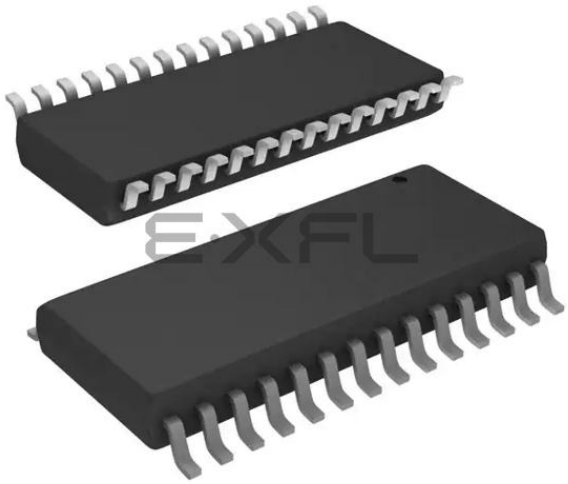

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PSMC, PWM, WDT
Number of I/O	24
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 11x12b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1783-e-so

3.1.1 READING PROGRAM MEMORY AS DATA

There are two methods of accessing constants in program memory. The first method is to use tables of RETLW instructions. The second method is to set an FSR to point to the program memory.

3.1.1.1 RETLW Instruction

The RETLW instruction can be used to provide access to tables of constants. The recommended way to create such a table is shown in Example 3-1.

EXAMPLE 3-1: RETLW INSTRUCTION

```
constants
    BRW                 ;Add Index in W to
                        ;program counter to
                        ;select data
    RETLW DATA0         ;Index0 data
    RETLW DATA1         ;Index1 data
    RETLW DATA2
    RETLW DATA3


my_function
    ;… LOTS OF CODE…
    MOVLW       DATA_INDEX
    call constants
    ;… THE CONSTANT IS IN W
```

The BRW instruction makes this type of table very simple to implement. If your code must remain portable with previous generations of microcontrollers, then the BRW instruction is not available so the older table read method must be used.

3.1.1.2 Indirect Read with FSR

The program memory can be accessed as data by setting bit 7 of the FSRxH register and reading the matching INDFx register. The MOVIW instruction will place the lower 8 bits of the addressed word in the W register. Writes to the program memory cannot be performed via the INDF registers. Instructions that access the program memory via the FSR require one extra instruction cycle to complete. Example 3-2 demonstrates accessing the program memory via an FSR.

The high directive will set bit<7> if a label points to a location in program memory.

EXAMPLE 3-2: ACCESSING PROGRAM MEMORY VIA FSR

```
constants
    RETLW DATA0         ;Index0 data
    RETLW DATA1         ;Index1 data
    RETLW DATA2
    RETLW DATA3
my_function
    ;… LOTS OF CODE…
    MOVLW   LOW constants
    MOVWF   FSR1L
    MOVLW   HIGH constants
    MOVWF   FSR1H
    MOVIW   0[FSR1]
;THE PROGRAM MEMORY IS IN W
```

3.3.4 DEVICE MEMORY MAPS

The memory maps for Bank 0 through Bank 31 are shown in the tables in this section.

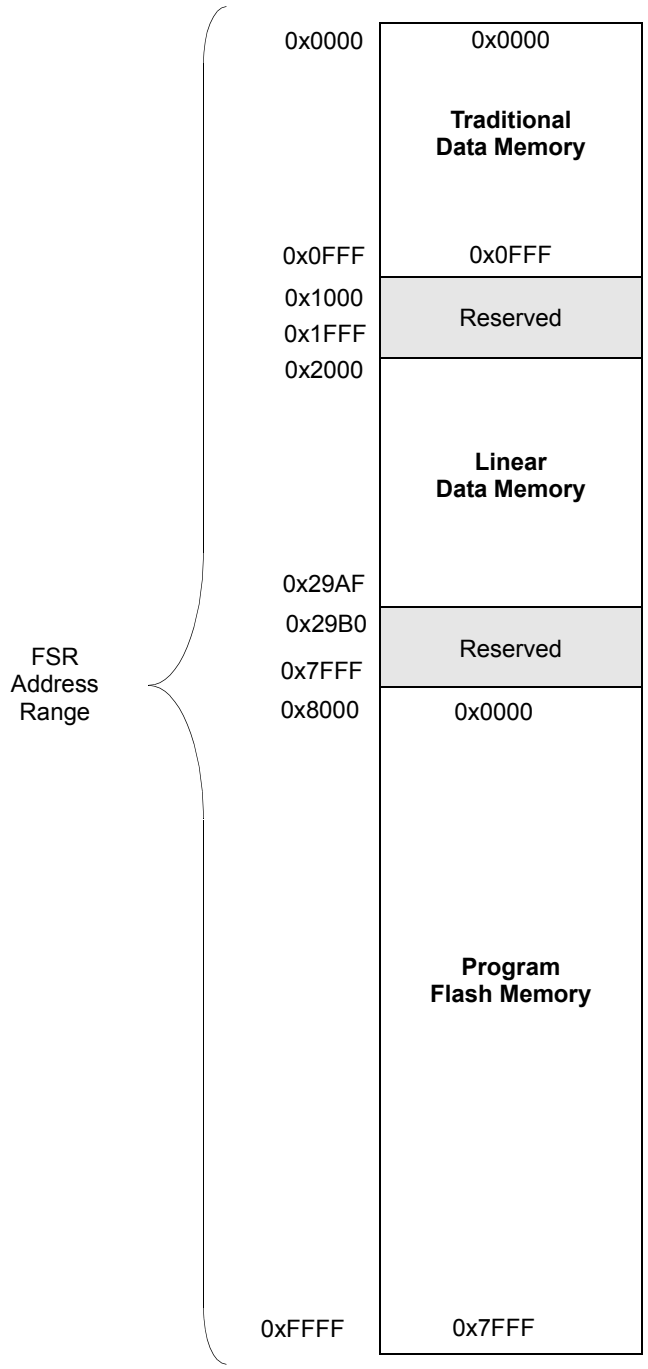
TABLE 3-3: PIC16(L)F1782/3 MEMORY MAP (BANKS 0-7)

BANK 0		BANK 1		BANK 2		BANK 3		BANK 4		BANK 5		BANK 6		BANK 7	
000h	Core Registers (Table 3-2)	080h	Core Registers (Table 3-2)	100h	Core Registers (Table 3-2)	180h	Core Registers (Table 3-2)	200h	Core Registers (Table 3-2)	280h	Core Registers (Table 3-2)	300h	Core Registers (Table 3-2)	380h	Core Registers (Table 3-2)
00Bh		08Bh		10Bh		18Bh		20Bh		28Bh		30Bh		38Bh	
00Ch	PORTA	08Ch	TRISA	10Ch	LATA	18Ch	ANSELA	20Ch	WPUA	28Ch	ODCONA	30Ch	SLRCONA	38Ch	INLVLA
00Dh	PORTB	08Dh	TRISB	10Dh	LATB	18Dh	ANSELB	20Dh	WPUB	28Dh	ODCONB	30Dh	SLRCONB	38Dh	INLVLB
00Eh	PORTC	08Eh	TRISC	10Eh	LATC	18Eh	—	20Eh	WPUC	28Eh	ODCONC	30Eh	SLRCONC	38Eh	INLVLC
00Fh	—	08Fh	—	10Fh	—	18Fh	—	20Fh	—	28Fh	—	30Fh	—	38Fh	—
010h	PORTE	090h	TRISE	110h	—	190h	—	210h	WPUE	290h	—	310h	—	390h	INLVLE
011h	PIR1	091h	PIE1	111h	CM1CON0	191h	EEADRL	211h	SSP1BUF	291h	CCPR1L	311h	—	391h	IOCAP
012h	PIR2	092h	PIE2	112h	CM1CON1	192h	EEADRH	212h	SSP1ADD	292h	CCPR1H	312h	—	392h	IOCAN
013h	—	093h	—	113h	CM2CON0	193h	EEDATL	213h	SSP1MSK	293h	CCP1CON	313h	—	393h	IOCAF
014h	PIR4	094h	PIE4	114h	CM2CON1	194h	EEDATH	214h	SSP1STAT	294h	—	314h	—	394h	IOCBP
015h	TMR0	095h	OPTION_REG	115h	CMOUT	195h	EECON1	215h	SSP1CON1	295h	—	315h	—	395h	IOCBN
016h	TMR1L	096h	PCON	116h	BORCON	196h	EECON2	216h	SSP1CON2	296h	—	316h	—	396h	IOCBF
017h	TMR1H	097h	WDTCON	117h	FVRCON	197h	VREGCON(2)	217h	SSP1CON3	297h	—	317h	—	397h	IOCCP
018h	T1CON	098h	OSCTUNE	118h	DACCON0	198h	—	218h	—	298h	CCPR2L	318h	—	398h	IOCCN
019h	T1GCON	099h	OSCCON	119h	DACCON1	199h	RCREG	219h	—	299h	CCPR2H	319h	—	399h	IOCCF
01Ah	TMR2	09Ah	OSCSTAT	11Ah	—	19Ah	TXREG	21Ah	—	29Ah	CCP2CON	31Ah	—	39Ah	—
01Bh	PR2	09Bh	ADRESL	11Bh	—	19Bh	SPBRG	21Bh	—	29Bh	—	31Bh	—	39Bh	—
01Ch	T2CON	09Ch	ADRESH	11Ch	—	19Ch	SPBRGH	21Ch	—	29Ch	—	31Ch	—	39Ch	—
01Dh	—	09Dh	ADCON0	11Dh	APFCON	19Dh	RCSTA	21Dh	—	29Dh	—	31Dh	—	39Dh	IOCEP
01Eh	—	09Eh	ADCON1	11Eh	CM3CON0	19Eh	TXSTA	21Eh	—	29Eh	—	31Eh	—	39Eh	IOCEN
01Fh	—	09Fh	ADCON2	11Fh	CM3CON1	19Fh	BAUDCON	21Fh	—	29Fh	—	31Fh	—	39Fh	IOCEF
020h	General Purpose Register 80 Bytes	0A0h	General Purpose Register 80 Bytes	120h	General Purpose Register 80 Bytes	1A0h	General Purpose Register 80 Bytes(1)	220h	General Purpose Register 80 Bytes(1)	2A0h	General Purpose Register 80 Bytes(1)	320h	General Purpose Register 16 Bytes(1)	3A0h	Unimplemented Read as '0'
06Fh		0EFh		16Fh		1EFh		26Fh		2EFh		32Fh		3EFh	
070h	Common RAM 70h – 7Fh	0F0h	Accesses 70h – 7Fh	170h	Accesses 70h – 7Fh	1F0h	Accesses 70h – 7Fh	270h	Accesses 70h – 7Fh	2F0h	Accesses 70h – 7Fh	330h	Unimplemented Read as '0'	3F0h	Accesses 70h – 7Fh
07Fh		0FFh		17Fh		1FFh		27Fh		2FFh		36Fh		3FFh	

Legend: = Unimplemented data memory locations, read as '0'.

Note 1: PIC16(L)F1783 only.
2: PIC16F1782/3 only.

FIGURE 3-9: INDIRECT ADDRESSING



Note: Not all memory regions are completely implemented. Consult device memory tables for memory limits.

5.0 RESETS

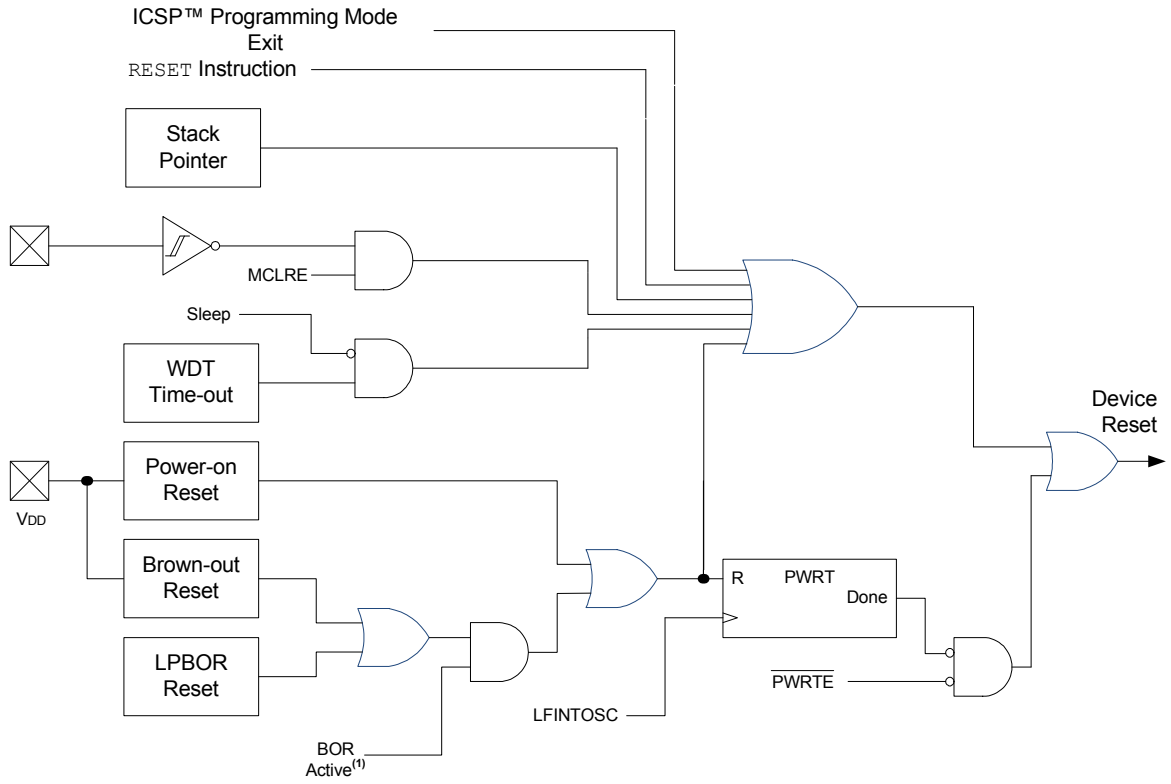
There are multiple ways to reset this device:

- Power-On Reset (POR)
- Brown-Out Reset (BOR)
- Low-Power Brown-Out Reset (LPBOR)
- $\overline{\text{MCLR}}$ Reset
- WDT Reset
- RESET instruction
- Stack Overflow
- Stack Underflow
- Programming mode exit

To allow VDD to stabilize, an optional Power-up Timer can be enabled to extend the Reset time after a BOR or POR event.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 5-1.

FIGURE 5-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: See Table 5-1 for BOR active conditions.

FIGURE 6-7: INTERNAL OSCILLATOR SWITCH TIMING

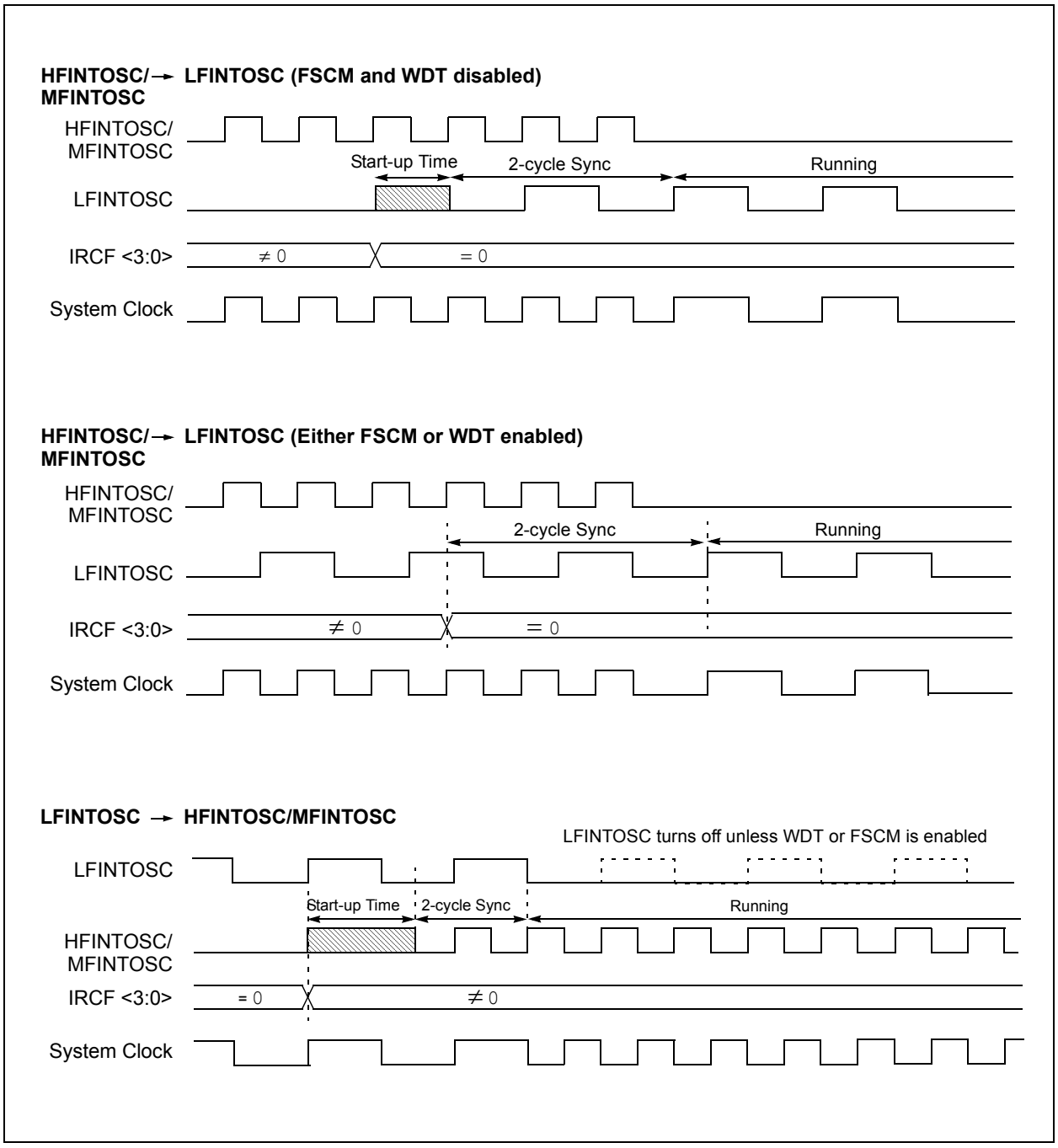
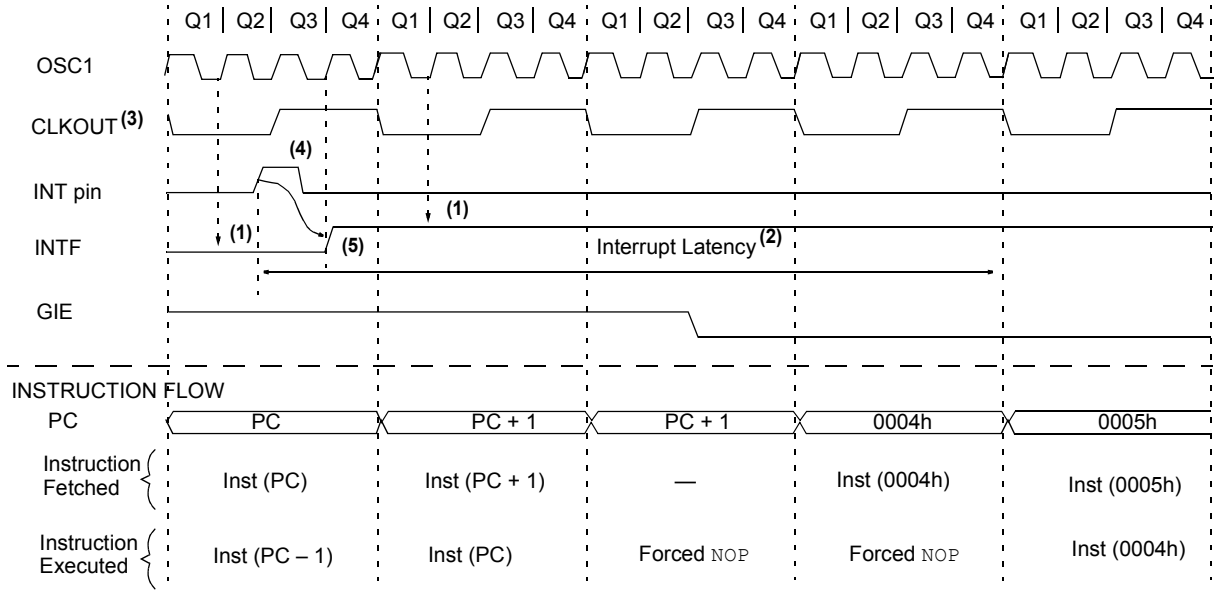


FIGURE 8-3: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Asynchronous interrupt latency = 3-5 TCY. Synchronous latency = 3-4 TCY, where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT not available in all oscillator modes.

4: For minimum width of INT pulse, refer to AC specifications in **Section 30.0 "Electrical Specifications"**".

5: INTF is enabled to be set any time during the Q4-Q1 cycles.

10.0 LOW DROPOUT (LDO) VOLTAGE REGULATOR

The “F” devices have an internal Low Dropout Regulator (LDO) which provide operation above 3.6V. The LDO regulates a voltage for the internal device logic while permitting the VDD and I/O pins to operate at a higher voltage. There is no user enable/disable control available for the LDO, it is always active. The “LF” devices operate at a maximum VDD of 3.6V and does not incorporate an LDO.

A device I/O pin may be configured as the LDO voltage output, identified as the VCAP pin. Although not required, an external low-ESR capacitor may be connected to the VCAP pin for additional regulator stability.

The $\overline{\text{VCAPEN}}$ bit of Configuration Words determines if which pin is assigned as the VCAP pin. Refer to Table 10-1.

TABLE 10-1: $\overline{\text{VCAPEN}}$ SELECT BIT

$\overline{\text{VCAPEN}}$	Pin
1	No VCAP
0	RA6

On power-up, the external capacitor will load the LDO voltage regulator. To prevent erroneous operation, the device is held in Reset while a constant current source charges the external capacitor. After the cap is fully charged, the device is released from Reset. For more information on the constant current rate, refer to the LDO Regulator Characteristics Table in **Section 30.0 “Electrical Specifications”**.

TABLE 10-2: SUMMARY OF CONFIGURATION WORD WITH LDO

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG2	13:8	—	—	LVP	$\overline{\text{DEBUG}}$	$\overline{\text{LPBOR}}$	BORV	STVREN	PLLEN	42
	7:0	—	—	$\overline{\text{VCAPEN}}$(1)	—	—	—	WRT<1:0>		

Legend: — = unimplemented locations read as ‘0’. Shaded cells are not used by LDO.

Note 1: “F” devices only.

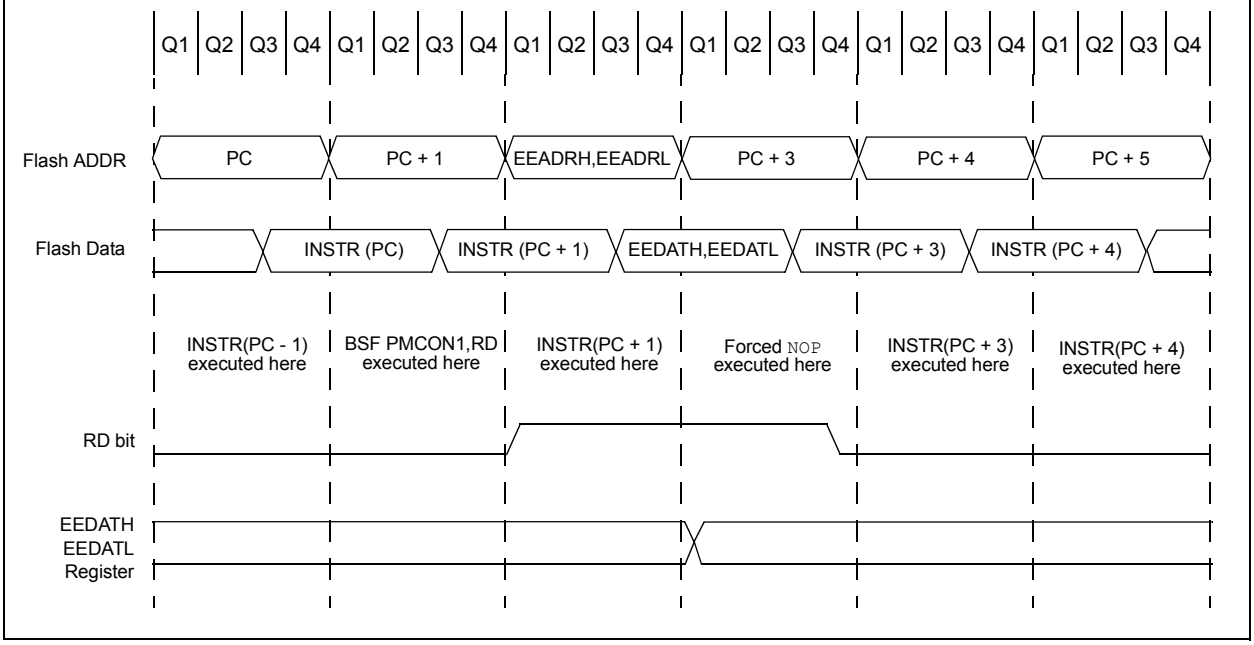
EXAMPLE 12-2: DATA EEPROM WRITE

Required Sequence

```
BANKSEL  EEADRL          ;
MOVLW    DATA_EE_ADDR    ;
MOVWF    EEADRL          ;Data Memory Address to write
MOVLW    DATA_EE_DATA    ;
MOVWF    EEDATL          ;Data Memory Value to write
BCF      EECON1, CFGS    ;Deselect Configuration space
BCF      EECON1, EEPGD   ;Point to DATA memory
BSF      EECON1, WREN    ;Enable writes

BCF      INTCON, GIE     ;Disable INTs.
MOVLW    55h             ;
MOVWF    EECON2          ;Write 55h
MOVLW    0AAh            ;
MOVWF    EECON2          ;Write AAh
BSF      EECON1, WR      ;Set WR bit to begin write
BSF      INTCON, GIE     ;Enable Interrupts
BCF      EECON1, WREN    ;Disable writes
BTFSC    EECON1, WR      ;Wait for write to complete
GOTO     $-2             ;Done
```

FIGURE 12-1: FLASH PROGRAM MEMORY READ CYCLE EXECUTION



13.8 Register Definitions: PORTC

REGISTER 13-18: PORTC: PORTC REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **RC<7:0>**: PORTC General Purpose I/O Pin bits(1)
1 = Port pin is ≥ VIH
0 = Port pin is ≤ VIL

Note 1: Writes to PORTC are actually written to corresponding LATC register. Reads from PORTC register is return of actual I/O pin values.

REGISTER 13-19: TRISC: PORTC TRI-STATE REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **TRISC<7:0>:** PORTC Tri-State Control bits
1 = PORTC pin configured as an input (tri-stated)
0 = PORTC pin configured as an output

REGISTER 13-20: LATC: PORTC DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **LATC<7:0>**: PORTC Output Latch Value bits(1)

Note 1: Writes to PORTC are actually written to corresponding LATC register. Reads from PORTC register is return of actual I/O pin values.

19.0 DIGITAL-TO-ANALOG CONVERTER (DAC) MODULE

The Digital-to-Analog Converter supplies a variable voltage reference, ratiometric with the input source, with 256 selectable output levels.

The input of the DAC can be connected to:

- External VREF pins
- VDD supply voltage
- FVR (Fixed Voltage Reference)

The output of the DAC can be configured to supply a reference voltage to the following:

- Comparator positive input
- Op amp positive input
- ADC input channel
- DACOUT1 pin
- DACOUT2 pin

The Digital-to-Analog Converter (DAC) is enabled by setting the DACEN bit of the DACCON0 register.

19.1 Output Voltage Selection

The DAC has 256 voltage level ranges. The 256 levels are set with the DACR<7:0> bits of the DACCON1 register.

The DAC output voltage is determined by Equation 19-1:

EQUATION 19-1: DAC OUTPUT VOLTAGE

$$\underline{IF\ DACxEN = 1}$$

$$V_{OUT} = \left((V_{SOURCE+} - V_{SOURCE-}) \times \frac{DACxR[7:0]}{2^8} \right) + V_{SOURCE-}$$

$$V_{SOURCE+} = V_{DD},\ V_{REF},\ or\ FVR\ BUFFER\ 2$$

$$V_{SOURCE-} = V_{SS}$$

19.2 Ratiometric Output Level

The DAC output value is derived using a resistor ladder with each end of the ladder tied to a positive and negative voltage reference input source. If the voltage of either input source fluctuates, a similar fluctuation will result in the DAC output value.

The value of the individual resistors within the ladder can be found in **Section 30.0 "Electrical Specifications"**.

19.3 DAC Voltage Reference Output

The DAC voltage can be output to the DACOUT1 and DACOUT2 pins by setting the respective DACOE1 and DACOE2 pins of the DACCON0 register. Selecting the DAC reference voltage for output on either DACOUTx pin automatically overrides the digital output buffer and digital input threshold detector functions of that pin. Reading the DACOUTx pin when it has been configured for DAC reference voltage output will always return a '0'.

Due to the limited current drive capability, a buffer must be used on the DAC voltage reference output for external connections to either DACOUTx pin. Figure 19-2 shows an example buffering technique.

REGISTER 20-2: CMxCON1: COMPARATOR Cx CONTROL REGISTER 1

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
CxINTP	CxINTN	CxPCH<2:0>			CxNCH<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **CxINTP:** Comparator Interrupt on Positive Going Edge Enable bits
1 = The CxIF interrupt flag will be set upon a positive going edge of the CxOUT bit
0 = No interrupt flag will be set on a positive going edge of the CxOUT bit

bit 6 **CxINTN:** Comparator Interrupt on Negative Going Edge Enable bits
1 = The CxIF interrupt flag will be set upon a negative going edge of the CxOUT bit
0 = No interrupt flag will be set on a negative going edge of the CxOUT bit

bit 5-3 **CxPCH<2:0>:** Comparator Positive Input Channel Select bits
111 = CxVP connects to AGND
110 = CxVP connects to FVR Buffer 2
101 = CxVP connects to DAC_output
100 = Reserved, input floating
011 = Reserved, input floating
010 = Reserved, input floating
001 = CxVP connects to CxIN1+ pin
000 = CxVP connects to CxIN0+ pin

bit 2-0 **CxNCH<2:0>:** Comparator Negative Input Channel Select bits
111 = CxVN connects to AGND
110 = CxVN unconnected, input floating
101 = Reserved, input floating
100 = Reserved, input floating
011 = CxVN connects to CxIN3- pin
010 = CxVN connects to CxIN2- pin
001 = CxVN connects to CxIN1- pin
000 = CxVN connects to CxIN0- pin

24.3.8 PULSE-SKIPPING PWM WITH COMPLEMENTARY OUTPUTS

The pulse-skipping PWM is used to generate a series of fixed-length pulses that may or not be triggered at each period event. If any of the sources enabled to generate a rising edge event are high when a period event occurs, a pulse will be generated. If the rising edge sources are low at the period event, no pulse will be generated.

The rising edge occurs based upon the value in the PSMCxPH register pair.

The falling edge event always occurs according to the enabled event inputs without qualification between any two inputs.

24.3.8.1 Mode Features

- Dead-band control is available
- No steering control available
- Primary PWM is output on only PSMCxA.
- Complementary PWM is output on only PSMCxB.

24.3.8.2 Waveform Generation

Rising Edge Event

If any enabled asynchronous rising edge event = 1 when there is a period event, then upon the next synchronous rising edge event:

- Complementary output is set inactive
- Dead-band rising is activated (if enabled)
- Primary output is set active

Falling Edge Event

- Primary output is set inactive
- Dead-band falling is activated (if enabled)
- Complementary output is set active

Note:	To use this mode, an external source must be used for the determination of whether or not to generate the set pulse. If the phase time base is used, it will either always generate a pulse or never generate a pulse based on the PSMCxPH value.

FIGURE 24-11: PULSE-SKIPPING WITH COMPLEMENTARY OUTPUT PWM WAVEFORM

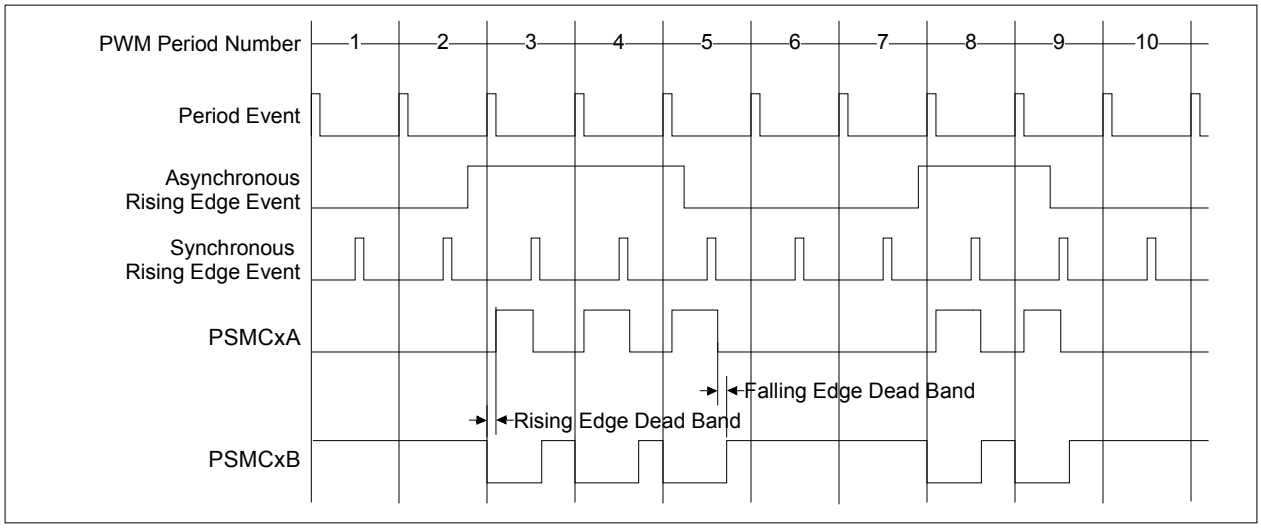
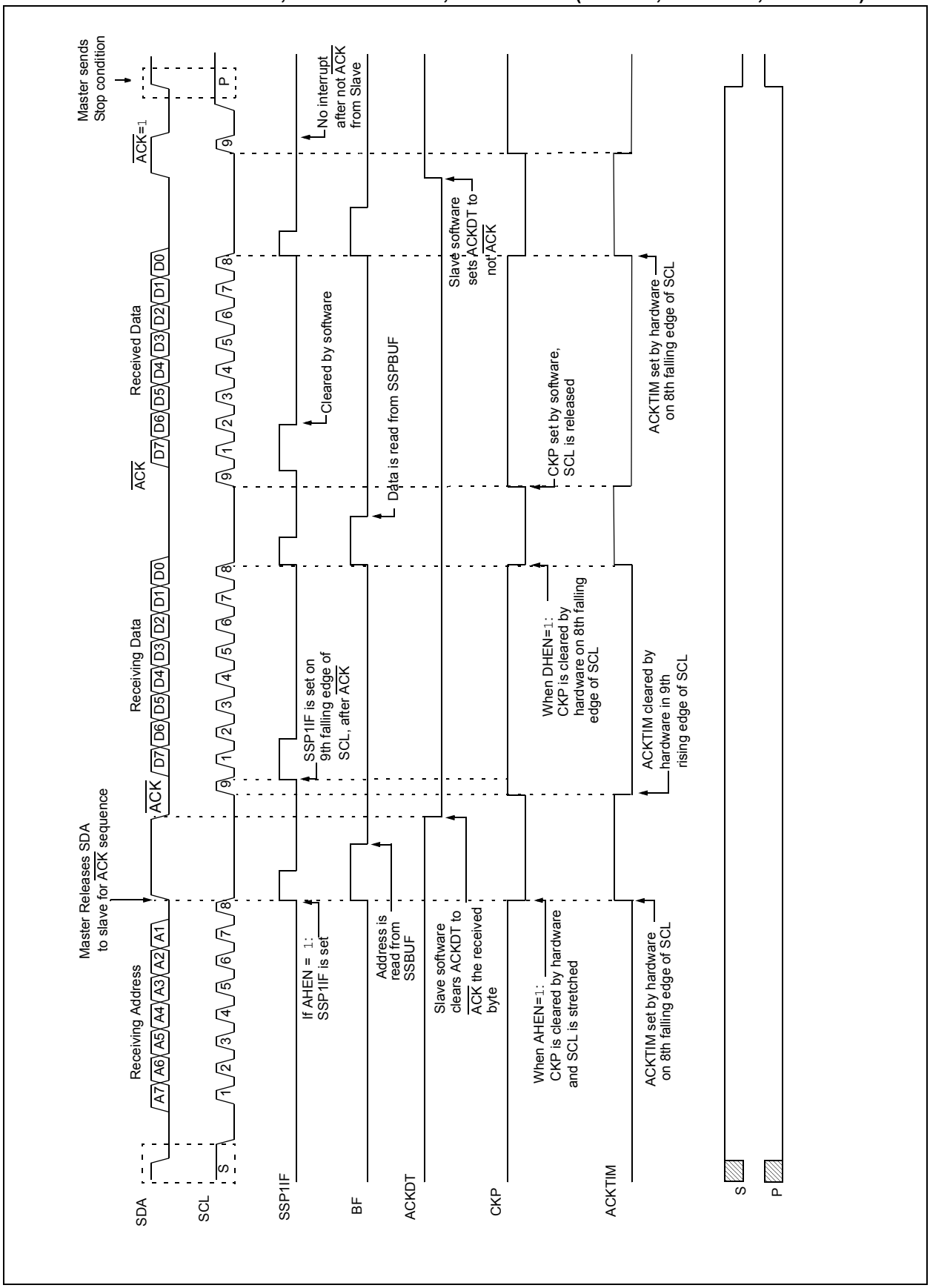


FIGURE 26-16: I²C SLAVE, 7-BIT ADDRESS, RECEPTION (SEN = 0, AHEN = 1, DHEN = 1)



26.5.4 SLAVE MODE 10-BIT ADDRESS RECEPTION

This section describes a standard sequence of events for the MSSP module configured as an I^2C slave in 10-bit Addressing mode.

Figure 26-19 is used as a visual reference for this description.

This is a step by step process of what must be done by slave software to accomplish I^2C communication.

1. Bus starts Idle.
2. Master sends Start condition; S bit of SSPSTAT is set; SSP1IF is set if interrupt on Start detect is enabled.
3. Master sends matching high address with R/$\overline{W}$ bit clear; UA bit of the SSPSTAT register is set.
4. Slave sends $\overline{ACK}$ and SSP1IF is set.
5. Software clears the SSP1IF bit.
6. Software reads received address from SSPBUF clearing the BF flag.
7. Slave loads low address into SSPADD, releasing SCL.
8. Master sends matching low address byte to the slave; UA bit is set.

Note: Updates to the SSPADD register are not allowed until after the $\overline{ACK}$ sequence.

9. Slave sends $\overline{ACK}$ and SSP1IF is set.

Note: If the low address does not match, SSP1IF and UA are still set so that the slave software can set SSPADD back to the high address. BF is not set because there is no match. CKP is unaffected.

10. Slave clears SSP1IF.
11. Slave reads the received matching address from SSPBUF clearing BF.
12. Slave loads high address into SSPADD.
13. Master clocks a data byte to the slave and clocks out the slaves $\overline{ACK}$ on the 9th SCL pulse; SSP1IF is set.
14. If SEN bit of SSPCON2 is set, CKP is cleared by hardware and the clock is stretched.
15. Slave clears SSP1IF.
16. Slave reads the received byte from SSPBUF clearing BF.
17. If SEN is set the slave sets CKP to release the SCL.
18. Steps 13-17 repeat for each received byte.
19. Master sends Stop to end the transmission.

26.5.5 10-BIT ADDRESSING WITH ADDRESS OR DATA HOLD

Reception using 10-bit addressing with AHEN or DHEN set is the same as with 7-bit modes. The only difference is the need to update the SSPADD register using the UA bit. All functionality, specifically when the CKP bit is cleared and SCL line is held low are the same. Figure 26-20 can be used as a reference of a slave in 10-bit addressing with AHEN set.

Figure 26-21 shows a standard waveform for a slave transmitter in 10-bit Addressing mode.

CALL **Call Subroutine**

Syntax:	[*label*] CALL k
Operands:	$0 \le k \le 2047$
Operation:	(PC)+ 1→ TOS, k → PC<10:0>, (PCLATH<6:3>) → PC<14:11>
Status Affected:	None
Description:	Call Subroutine. First, return address (PC + 1) is pushed onto the stack. The eleven-bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a 2-cycle instruction.

CALLW **Subroutine Call With W**

Syntax:	[*label*] CALLW
Operands:	None
Operation:	(PC) +1 → TOS, (W) → PC<7:0>, (PCLATH<6:0>) → PC<14:8>
Status Affected:	None
Description:	Subroutine call with W. First, the return address (PC + 1) is pushed onto the return stack. Then, the contents of W is loaded into PC<7:0>, and the contents of PCLATH into PC<14:8>. CALLW is a 2-cycle instruction.

CLRF **Clear f**

Syntax:	[*label*] CLRF f
Operands:	$0 \le f \le 127$
Operation:	00h → (f) 1 → Z
Status Affected:	Z
Description:	The contents of register 'f' are cleared and the Z bit is set.

CLRW **Clear W**

Syntax:	[*label*] CLRW
Operands:	None
Operation:	00h → (W) 1 → Z
Status Affected:	Z
Description:	W register is cleared. Zero bit (Z) is set.

CLRWDT **Clear Watchdog Timer**

Syntax:	[*label*] CLRWDT
Operands:	None
Operation:	00h → WDT 0 → WDT prescaler, 1 → $\overline{TO}$ 1 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$
Description:	CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

COMF **Complement f**

Syntax:	[*label*] COMF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	($\bar{f}$) → (destination)
Status Affected:	Z
Description:	The contents of register 'f' are complemented. If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f'.

DECF **Decrement f**

Syntax:	[*label*] DECF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) - 1 → (destination)
Status Affected:	Z
Description:	Decrement register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

MOVIW **Move INDFn to W**

Syntax: [*label*] MOVIW ++FSRn
[*label*] MOVIW --FSRn
[*label*] MOVIW FSRn++
[*label*] MOVIW FSRn--
[*label*] MOVIW k[FSRn]

Operands: n ∈ [0,1]
mm ∈ [00,01, 10, 11]
-32 ≤ k ≤ 31

Operation: INDFn → W
Effective address is determined by
- FSR + 1 (preincrement)
- FSR - 1 (predecrement)
- FSR + k (relative offset)

After the Move, the FSR value will be either:
- FSR + 1 (all increments)
- FSR - 1 (all decrements)
- Unchanged

Status Affected: Z

Mode	Syntax	mm
Preincrement	++FSRn	00
Predecrement	--FSRn	01
Postincrement	FSRn++	10
Postdecrement	FSRn--	11

Description: This instruction is used to move data between W and one of the indirect registers (INDFn). Before/after this move, the pointer (FSRn) is updated by pre/post incrementing/decrementing it.

Note: The INDFn registers are not physical registers. Any instruction that accesses an INDFn register actually accesses the register at the address specified by the FSRn.

FSRn is limited to the range 0000h - FFFFh. Incrementing/decrementing it beyond these bounds will cause it to wrap-around.

MOVLB **Move literal to BSR**

Syntax: [*label*] MOVLB k

Operands: 0 ≤ k ≤ 31

Operation: k → BSR

Status Affected: None

Description: The 5-bit literal 'k' is loaded into the Bank Select Register (BSR).

MOVLP **Move literal to PCLATH**

Syntax: [*label*] MOVLP k

Operands: 0 ≤ k ≤ 127

Operation: k → PCLATH

Status Affected: None

Description: The 7-bit literal 'k' is loaded into the PCLATH register.

MOVLW **Move literal to W**

Syntax: [*label*] MOVLW k

Operands: 0 ≤ k ≤ 255

Operation: k → (W)

Status Affected: None

Description: The 8-bit literal 'k' is loaded into W register. The "don't cares" will assemble as '0's.

Words: 1

Cycles: 1

Example:
```
MOVLW   0x5A
```
After Instruction
W = 0x5A

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f

Operands: 0 ≤ f ≤ 127

Operation: (W) → (f)

Status Affected: None

Description: Move data from W register to register 'f'.

Words: 1

Cycles: 1

Example:
```
MOVWF   OPTION_REG
```
Before Instruction
OPTION_REG = 0xFF
W = 0x4F
After Instruction
OPTION_REG = 0x4F
W = 0x4F

Note: Unless otherwise noted, VIN = 5V, FOSC = 300 kHz, CIN = 0.1 µF, TA = 25°C.

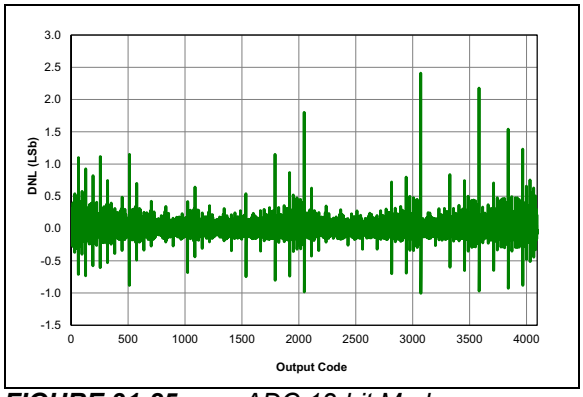


FIGURE 31-85: *ADC 12-bit Mode, Single-Ended DNL, VDD = 3.0V, TAD = 1 µS, 25°C.*

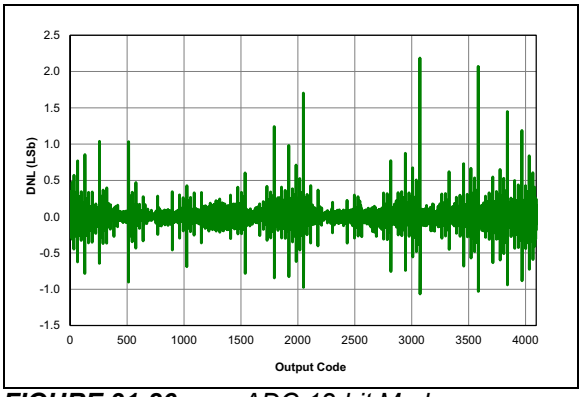


FIGURE 31-86: *ADC 12-bit Mode, Single-Ended DNL, VDD = 3.0V, TAD = 4 µS, 25°C.*

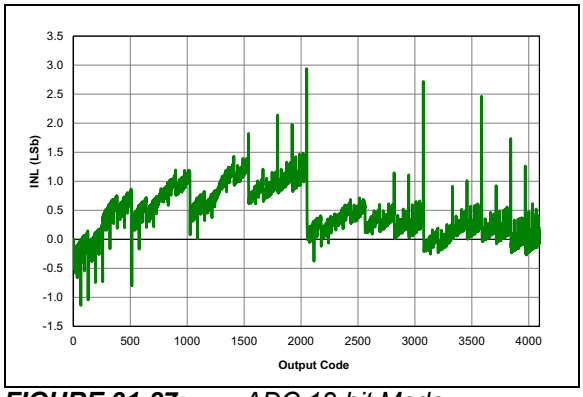


FIGURE 31-87: *ADC 12-bit Mode, Single-Ended INL, VDD = 3.0V, TAD = 1 µS, 25°C.*

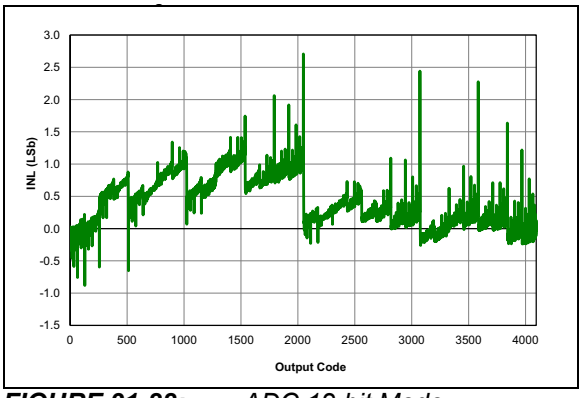


FIGURE 31-88: *ADC 12-bit Mode, Single-Ended INL, VDD = 3.0V, TAD = 4 µS, 25°C.*

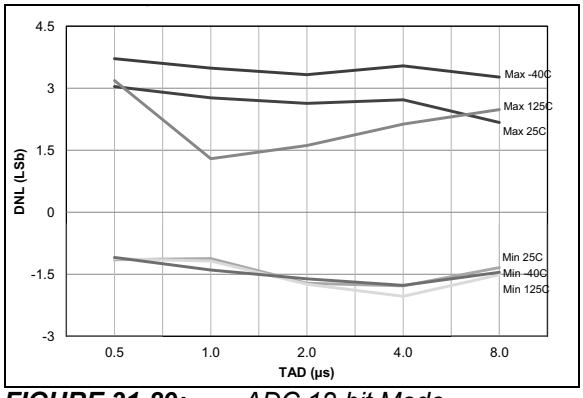


FIGURE 31-89: *ADC 12-bit Mode, Single-Ended DNL, VDD = 3.0V, VREF = 3.0V.*

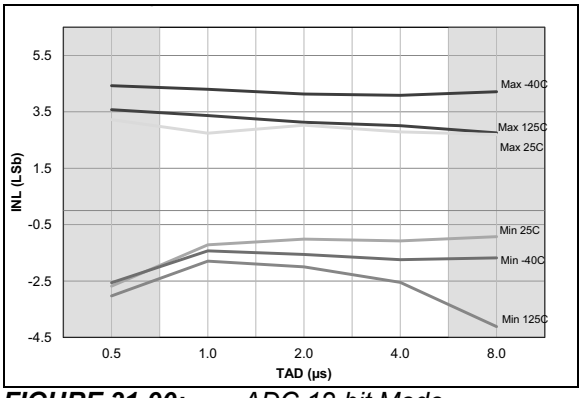


FIGURE 31-90: *ADC 12-bit Mode, Single-Ended INL, VDD = 3.0V, VREF = 3.0V.*

32.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB XC Compiler
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB X SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
  - MPLAB ICD 3
  - PICkit™ 3
- Device Programmers
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

32.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

Project-Based Workspaces:

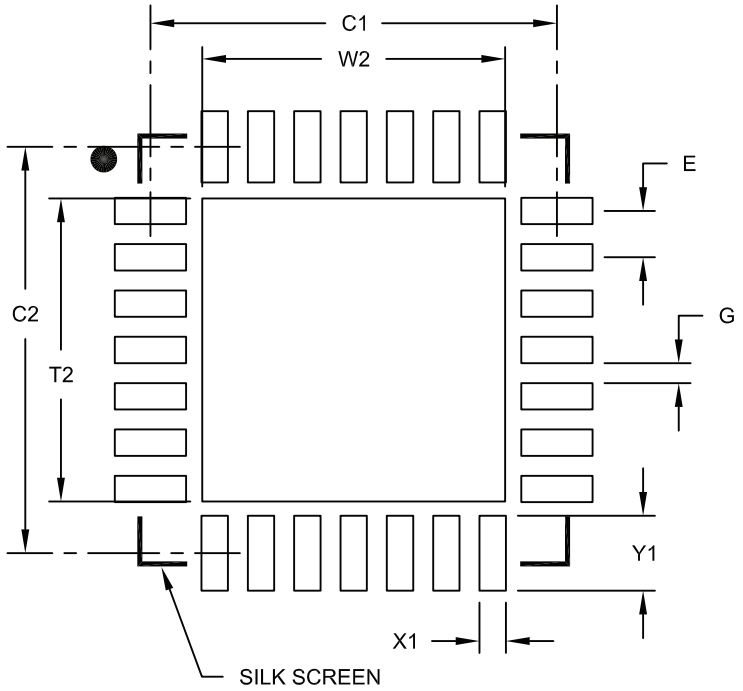
- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			4.25
Optional Center Pad Length	T2			4.25
Contact Pad Spacing	C1		5.70	
Contact Pad Spacing	C2		5.70	
Contact Pad Width (X28)	X1			0.37
Contact Pad Length (X28)	Y1			1.00
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2105A

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

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